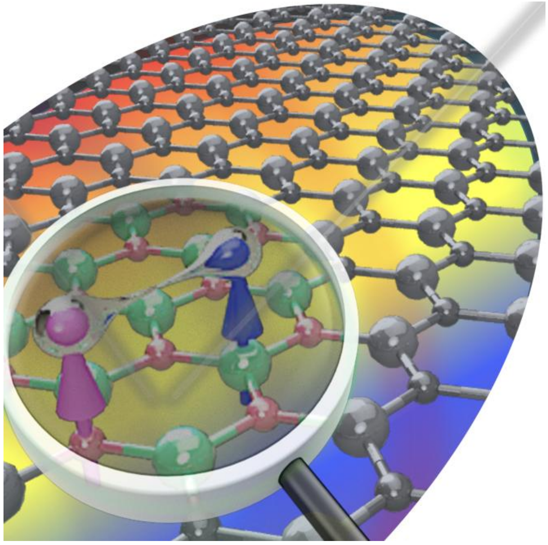
Joint Special Topic
Advances in Spectroscopic Ellipsometry methods and materials characterization
Applied Physics Letters & Journal of Applied Physics & AIP Advances

Submission opens June 2025 - Closes November 2025

Machine Learning/Artificial Intelligence + Imaging instrumentation, approaches, and applications + Advanced Instrumentation and Modeling + Pump-probe & fs/ps time-resolved ellipsometry + In-situ and real-time process control in thin film deposition techniques ALD, PLD, CVD etc. + Terahertz instrumentations and applications + Wideband gap and Ultrawideband gap semiconductors + Industrial applications + Anisotropic materials + Low-dimensional and topological materials + Organic materials and organic electronics + Extended ultraviolet instrumentation and applications + Semiconductor hetero- and device structures + Biological materials and life science applications



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